

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034



ON Semiconductor®

www.onsemi.com

Operational Amplifiers, High Slew Rate, Low Voltage, Rail-to-Rail Output

The NCS2003 family of op amps features high slew rate, low voltage operation with rail-to-rail output drive capability. The 1.8 V operation allows high performance operation in low voltage, low power applications. The fast slew rate and wide unity-gain bandwidth (5 MHz at 1.8 V) make these op amps suited for high speed applications. The low input offset voltage (4 mV max) allows the op amp to be used for current shunt monitoring. Additional features include no output phase reversal with overdriven inputs and ultra low input bias current of 1 pA.

The NCS2003 family is the ideal solution for a wide range of applications and products. The single channel NCS2003, dual channel NCS20032, and quad channel NCS20034 are available in a variety of compact and space-saving packages. The NCV prefix denotes that the device is AEC-Q100 Qualified and PPAP Capable.

Features

- Unity Gain Bandwidth: 7 MHz at $V_S = 5\text{ V}$
- Fast Slew Rate: 8 V/ μs rising, 12.5 V/ μs falling at $V_S = 5\text{ V}$
- Rail-to-Rail Output
- No Output Phase Reversal for Over-Driven Input Signals
- Low Offset Voltage: 0.5 mV typical
- Low Input Bias Current: 1 pA typical
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Current Shunt Monitor
- Signal Conditioning
- Active Filter
- Sensor Buffer

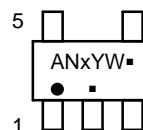
End Products

- Motor Control Drives
- Hard Drives
- Medical Devices
- White Goods and Air Conditioners

MARKING DIAGRAMS



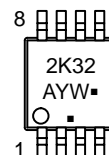
SOT23-5
CASE 483
(NCS/NCV2003)



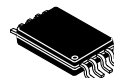
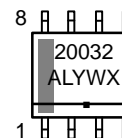
SOT553, 5 LEAD
CASE 463B
(NCS2003)



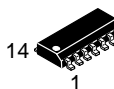
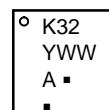
Micro8™
DM SUFFIX
CASE 846A



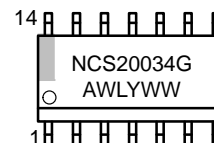
SOIC-8
CASE 751



TSSOP-8
T SUFFIX
CASE 948S



SOIC-14 NB
CASE 751A



A = Assembly Location
WL, L = Wafer Lot
Y = Year
WW, W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 2 of this data sheet.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

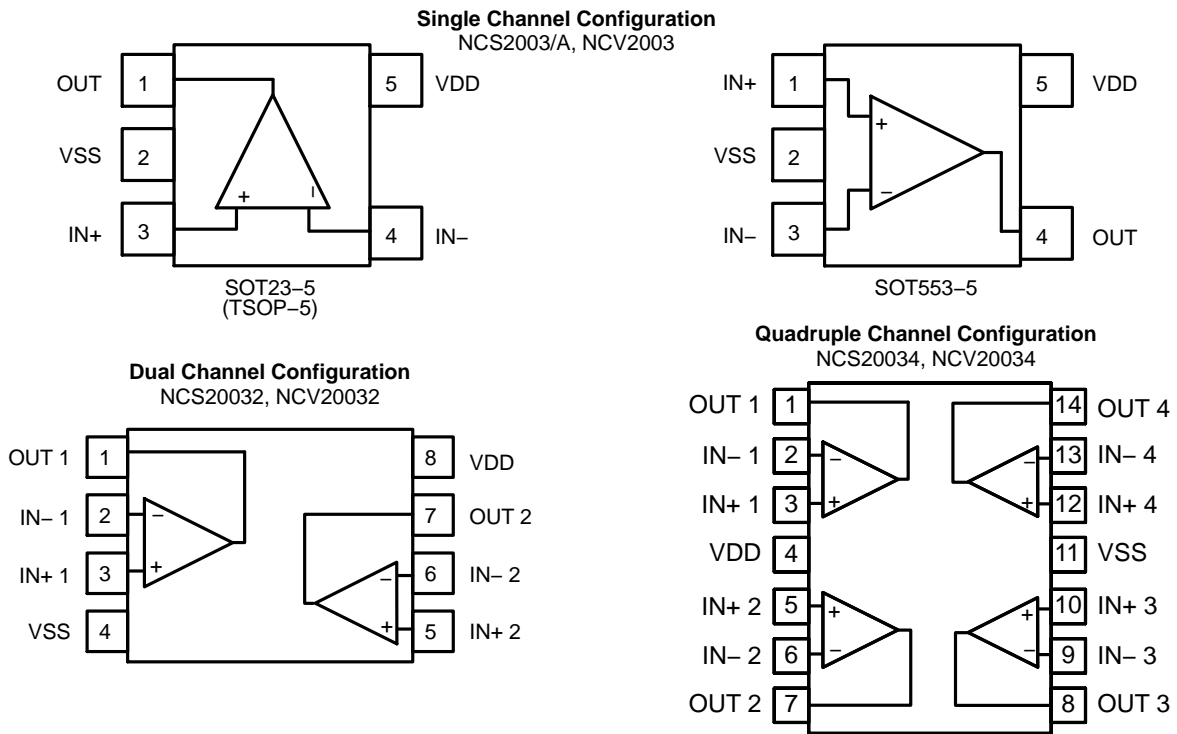


Figure 1. Pin Connections

ORDERING INFORMATION

| Device | Configuration | Automotive | Marking | Package | Shipping† |
|--------------------------------------|---------------|------------|-----------|-----------------------|----------------------|
| NCS2003SN2T1G | Single | No | AN3 | SOT23-5 (Pb-Free) | 3000 / Tape and Reel |
| NCS2003ASN2T1G | | No | AN4 | SOT23-5 (Pb-Free) | 3000 / Tape and Reel |
| NCS2003XV53T2G | | No | A3 | SOT553-5 (Pb-Free) | 4000 / Tape and Reel |
| NCV2003SN2T1G* | | Yes | AN3 | SOT23-5 (Pb-Free) | 3000 / Tape and Reel |
| NCS20032DMR2G (In Development)** | Dual | No | 2K32 | Micro8 (Pb-Free) | 4000 / Tape and Reel |
| NCS20032DR2G | | | 20032 | SOIC-8 (Pb-Free) | 2500 / Tape and Reel |
| NCS20032DTBR2G (In Development)** | | | K32 | TSSOP-8 (Pb-Free) | 3000 / Tape and Reel |
| NCV20032DMR2G* (In Development)** | | Yes | 2K32 | Micro8 (Pb-Free) | 4000 / Tape and Reel |
| NCV20032DR2G* | | | 20032 | SOIC-8 (Pb-Free) | 2500 / Tape and Reel |
| NCV20032DTBR2G* | | | K32 | TSSOP-8 (Pb-Free) | 3000 / Tape and Reel |
| NCS20034DR2G | Quad | No | NCS20034G | SOIC-14 (Pb-Free) | 2500 / Tape and Reel |
| NCV20034DR2G* | | Yes | NCS20034G | SOIC-14 (Pb-Free) | 2500 / Tape and Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D

*NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

**Contact local sales office for more information.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

ABSOLUTE MAXIMUM RATINGS

Over operating free-air temperature, unless otherwise stated

| Parameter | Symbol | Limit | Unit |
|--------------------------------------|--------|-------|------|
| Supply Voltage ($V_{DD} - V_{SS}$) | V_S | 7.0 | V |

INPUT AND OUTPUT PINS

| | | | |
|-------------------------------|----------|-----------------------|----|
| Input Voltage (Note 1) | V_{IN} | $V_{SS} - 0.3$ to 7.0 | V |
| Input Current | I_{IN} | 10 | mA |
| Output Short Current (Note 2) | I_O | 100 | mA |

TEMPERATURE

| | | | |
|----------------------|-----------|------------|----|
| Storage Temperature | T_{STG} | -65 to 150 | °C |
| Junction Temperature | T_J | 150 | °C |

ESD RATINGS (Note 3)

| | | | | |
|----------------------|------------------------------------|-----|----------------------|---|
| Human Body Model | NCx2003, A NCx20032 NCx20034 | HBM | 3000 2000 3000 | V |
| Machine Model | NCx2003, A NCx20032 NCx20034 | MM | 200 100 150 | V |
| Charged Device Model | NCx2003, A NCx2003x | CDM | 1000 2000 | V |

OTHER PARAMETERS

| | | | |
|-------------------------------------|----------|---------|----|
| Moisture Sensitivity Level (Note 5) | MSL | Level 1 | |
| Latch-up Current (Note 4) | I_{LU} | 100 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Neither input should exceed the range of $V_{SS} - 300$ mV to 7.0 V. This device contains internal protection diodes between the input pins and V_{DD} . When V_{IN} exceeds V_{DD} , the input current should be limited to the specified value.
- Indefinite duration; however, maximum package power dissipation limits must be observed to ensure that the maximum junction temperature is not exceeded.
- This device series incorporates ESD protection and is tested by the following methods:
ESD Human Body Model tested per AEC-Q100-002 and JESD22-A114
ESD Machine Model tested per AEC-Q100-003 and JESD22-A115
ESD Charged Device Model tested per AEC-Q100-011 and ANSI/ESD S5.3.1-2009
- Latch-up current tested per JEDEC Standard JESD78.
- Moisture Sensitivity Level tested per IPC/JEDEC standard J-STD-020A.

THERMAL INFORMATION

| Thermal Metric | Symbol | Package | Single Layer Board (Note 6) | Multi Layer Board (Note 7) | Unit |
|--|---------------|----------------|-----------------------------|----------------------------|------|
| Junction to Ambient Thermal Resistance | θ_{JA} | SOT23-5/TSOP-5 | 408 | 355 | °C/W |
| | | SOT553-5 | 428 | 406 | |
| | | Micro8/MSOP8 | 235 | 163 | |
| | | SOIC-8 | 240 | 179 | |
| | | TSSOP-8 | 300 | 238 | |
| | | SOIC-14 | 167 | 123 | |

6. Values based on a 1S standard PCB according to JEDEC51-3 with 1.0 oz copper and a 300 mm² copper area

7. Values based on a 1S2P standard PCB according to JEDEC51-7 with 1.0 oz copper and a 100 mm² copper area

RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min | Max | Unit |
|--|--|------------|--------------|------|
| Operating Supply Voltage ($V_{DD} - V_{SS}$) | V_S | 1.7 | 5.5 | V |
| Specified Operating Range | NCS2003, A NCV2003, NCx20032, NCx20034 T_A | -40 -40 | +85 +125 | °C |
| Input Common Mode Range | V_{CM} | V_{SS} | $V_{DD}-0.6$ | V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

ELECTRICAL CHARACTERISTICS: $V_S = +1.8\text{ V}$

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to midsupply, $V_{CM} = V_{OUT} = \text{midsupply}$, unless otherwise noted. **Boldface** limits apply over the specified temperature range. Guaranteed by design and/or characterization.

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|------------------------------|--------------------------|---|-----------|------------|-----|------------------------------|
| INPUT CHARACTERISTICS | | | | | | |
| Input Offset Voltage | V_{OS} | NCS2003A | | 0.5 | 3.0 | mV |
| | | NCx2003, NCx20032, NCx20034 | | 0.5 | 4.0 | mV |
| Offset Voltage Drift | $\Delta V_{OS}/\Delta T$ | | | 2.0 | | $\mu\text{V}/^\circ\text{C}$ |
| | | NCS2003A (Note 8) | | | 6.0 | $\mu\text{V}/^\circ\text{C}$ |
| Input Bias Current | I_{IB} | | | 1 | | pA |
| Input Offset Current | I_{OS} | | | 1 | | pA |
| Channel Separation | XTLK | DC, NCx20032, NCx20034 | | 100 | | dB |
| Input Resistance | R_{IN} | | | 1 | | $\text{T}\Omega$ |
| Input Capacitance | C_{IN} | | | 1.2 | | pF |
| Common Mode Rejection Ratio | CMRR | $V_{IN} = V_{SS}$ to $V_{DD} - 0.6\text{ V}$ | 70 | 80 | | dB |
| | | $V_{IN} = V_{SS} + 0.2\text{ V}$ to $V_{DD} - 0.6\text{ V}$ | 65 | | | |

OUTPUT CHARACTERISTICS

| | | | | | | | |
|------------------------------------|-----------|---------------------------|------------|-------------|-------|------------|----|
| Open Loop Voltage Gain | A_{VOL} | $R_L = 10\text{ k}\Omega$ | | 80 | 92 | dB | |
| | | | | 75 | | | |
| | | $R_L = 2\text{ k}\Omega$ | | | 92 | | |
| | | | | 70 | | | |
| Output Current Capability (Note 8) | I_{SC} | Sourcing | | 5 | 8 | mA | |
| | | Sinking | | 10 | 14 | | |
| Output Voltage High | V_{OH} | $R_L = 10\text{ k}\Omega$ | | 1.75 | 1.798 | V | |
| | | $R_L = 2\text{ k}\Omega$ | | 1.7 | 1.78 | | |
| Output Voltage Low | V_{OL} | $R_L = 10\text{ k}\Omega$ | NCx2003, A | | 7 | 50 | mV |
| | | | NCx2003x | | 7 | 100 | |
| | | $R_L = 2\text{ k}\Omega$ | | | | 20 | |

NOISE PERFORMANCE

| | | | | | | |
|-----------------------|-------|--------------------|--|-----|--|------------------------------|
| Voltage Noise Density | e_N | $f = 1\text{ kHz}$ | | 20 | | $\text{nV}/\sqrt{\text{Hz}}$ |
| Current Noise Density | i_N | $f = 1\text{ kHz}$ | | 0.1 | | $\text{pA}/\sqrt{\text{Hz}}$ |

DYNAMIC PERFORMANCE

| | | | | | | |
|-------------------------|----------|---|--------------------------|---|-----|------------------------|
| Gain Bandwidth Product | GBWP | | | 5 | | MHz |
| Slew Rate at Unity Gain | SR | Rising Edge, $R_L = 2\text{ k}\Omega$, $A_V = +1$ | | | 6 | $\text{V}/\mu\text{s}$ |
| | | Falling Edge, $R_L = 2\text{ k}\Omega$, $A_V = +1$ | | | 9 | |
| Phase Margin | ψ_m | $R_L = 10\text{ k}\Omega$, $C_L = 5\text{ pF}$ | | | 53 | $^\circ$ |
| Gain Margin | A_m | $R_L = 10\text{ k}\Omega$, $C_L = 5\text{ pF}$ | NCx2003, A | | 12 | dB |
| | | | NCx2003x | | 8 | |
| Settling Time | t_S | $V_O = 1\text{ V}_{pp}$, Gain = 1, $C_L = 20\text{ pF}$ | Settling time to 0.1% | | 1.8 | μs |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

8. Guaranteed by design and/or characterization.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

ELECTRICAL CHARACTERISTICS: $V_S = +1.8\text{ V}$

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to midsupply, $V_{CM} = V_{OUT} = \text{midsupply}$, unless otherwise noted. **Boldface** limits apply over the specified temperature range. Guaranteed by design and/or characterization.

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------|--------|------------|-----|-----|-----|------|
|-----------|--------|------------|-----|-----|-----|------|

DYNAMIC PERFORMANCE

| | | | | | | |
|------------------------------------|-------|---|--|-------|--|---|
| Total Harmonics Distortion + Noise | THD+N | $V_O = 1\text{ V}_{pp}$, $R_L = 2\text{ k}\Omega$, $A_V = +1$, $f = 1\text{ kHz}$ | | 0.005 | | % |
| | | $V_O = 1\text{ V}_{pp}$, $R_L = 2\text{ k}\Omega$, $A_V = +1$, $f = 10\text{ kHz}$ | | 0.025 | | |

POWER SUPPLY

| | | | | | | | |
|------------------------------|----------|----------------------|--------------------|-----------|-----|-------------|---------------|
| Power Supply Rejection Ratio | PSRR | NCx2003 | | 72 | 80 | | dB |
| | | | | 65 | | | |
| | | NCx20032, NCx20034 | | 80 | 100 | | |
| Quiescent Current | I_{DD} | No load, per channel | NCx2003, A | | 230 | 560 | μA |
| | | | | | | 1000 | |
| | | | NCx20032, NCx20034 | | 275 | 375 | |
| | | | | | | 575 | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

8. Guaranteed by design and/or characterization.

ELECTRICAL CHARACTERISTICS: $V_S = +5.0\text{ V}$

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to midsupply, $V_{CM} = V_{OUT} = \text{midsupply}$, unless otherwise noted. **Boldface** limits apply over the specified temperature range. Guaranteed by design and/or characterization.

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------|--------|------------|-----|-----|-----|------|
|-----------|--------|------------|-----|-----|-----|------|

INPUT CHARACTERISTICS

| | | | | | | |
|----------------------|--------------------------|------------------------|--|------------|------------|------------------------------|
| Input Offset Voltage | V_{OS} | NCS2003A | | 0.5 | 3.0 | mV |
| | | NCx2003 | | 0.5 | 4.0 | mV |
| | | NCx20032, NCx20034 | | | 5.0 | mV |
| Offset Voltage Drift | $\Delta V_{OS}/\Delta T$ | | | 2.0 | | $\mu\text{V}/^\circ\text{C}$ |
| | | NCS2003A (Note 9) | | | 6.0 | $\mu\text{V}/^\circ\text{C}$ |
| Input Bias Current | I_{IB} | | | 1 | | pA |
| Input Offset Current | I_{OS} | | | 1 | | pA |
| Channel Separation | XTLK | DC, NCx20032, NCx20034 | | 100 | | dB |
| Input Resistance | R_{IN} | | | 1 | | $\text{T}\Omega$ |
| Input Capacitance | C_{IN} | | | 1.2 | | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

9. Guaranteed by design and/or characterization.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

ELECTRICAL CHARACTERISTICS: $V_S = +5.0\text{ V}$

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to midsupply, $V_{CM} = V_{OUT} = \text{midsupply}$, unless otherwise noted. **Boldface** limits apply over the specified temperature range. Guaranteed by design and/or characterization.

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------|--------|------------|-----|-----|-----|------|
|-----------|--------|------------|-----|-----|-----|------|

INPUT CHARACTERISTICS

| | | | | | | | |
|-----------------------------|------|--------------------|---|-----------|----|--|----|
| Common Mode Rejection Ratio | CMRR | NCx2003, A | $V_{IN} = V_{SS}$ to $V_{DD} - 0.6\text{ V}$ | 65 | 90 | | dB |
| | | | $V_{IN} = V_{SS} + 0.2\text{ V}$ to $V_{DD} - 0.6\text{ V}$ | 63 | | | |
| | | NCx20032, NCx20034 | $V_{IN} = V_{SS}$ to $V_{DD} - 0.6\text{ V}$ | 70 | 90 | | |
| | | | $V_{IN} = V_{SS} + 0.2\text{ V}$ to $V_{DD} - 0.6\text{ V}$ | 65 | | | |

OUTPUT CHARACTERISTICS

| | | | | | | | |
|------------------------------------|-----------|---------------------------|------------|-------------|------|------------|----|
| Open Loop Voltage Gain | A_{VOL} | $R_L = 10\text{ k}\Omega$ | | 86 | 92 | | dB |
| | | | | 78 | | | |
| | | $R_L = 2\text{ k}\Omega$ | | 83 | 92 | | |
| | | | | 78 | | | |
| Output Current Capability (Note 9) | I_{SC} | Sourcing | | 40 | 76 | | mA |
| | | Sinking | | 50 | 96 | | |
| Output Voltage High | V_{OH} | $R_L = 10\text{ k}\Omega$ | | 4.95 | 4.99 | | V |
| | | $R_L = 2\text{ k}\Omega$ | | 4.9 | 4.97 | | |
| Output Voltage Low | V_{OL} | $R_L = 10\text{ k}\Omega$ | NCx2003, A | | 8 | 50 | mV |
| | | | NCx2003x | | 8 | 100 | |
| | | $R_L = 2\text{ k}\Omega$ | | | 24 | 100 | |

NOISE PERFORMANCE

| | | | | | | |
|-----------------------|-------|--------------------|--|-----|--|------------------------------|
| Voltage Noise Density | e_N | $f = 1\text{ kHz}$ | | 20 | | $\text{nV}/\sqrt{\text{Hz}}$ |
| Current Noise Density | i_N | $f = 1\text{ kHz}$ | | 0.1 | | $\text{pA}/\sqrt{\text{Hz}}$ |

DYNAMIC PERFORMANCE

| | | | | | | |
|------------------------------------|----------|---|--------------------------|-------|--|------------------------|
| Gain Bandwidth Product | GBWP | | | 7 | | MHz |
| Slew Rate at Unity Gain | SR | Rising Edge, $R_L = 2\text{ k}\Omega$, $A_V = +1$ | | 8 | | $\text{V}/\mu\text{s}$ |
| | | Falling Edge, $R_L = 2\text{ k}\Omega$, $A_V = +1$ | | 12.5 | | |
| Phase Margin | ψ_m | $R_L = 10\text{ k}\Omega$, $C_L = 5\text{ pF}$ | NCx2003, A | 64 | | $^\circ$ |
| | | | NCx2003x | 56 | | |
| Gain Margin | A_m | $R_L = 10\text{ k}\Omega$, $C_L = 5\text{ pF}$ | | 9 | | dB |
| Settling Time | t_S | $V_O = 1\text{ V}_{pp}$, Gain = 1, $C_L = 20\text{ pF}$ | Settling time to 0.1% | 0.6 | | μs |
| Total Harmonics Distortion + Noise | THD+N | $V_O = 4\text{ V}_{pp}$, $R_L = 2\text{ k}\Omega$, $A_V = +1$, $f = 1\text{ kHz}$ | | 0.002 | | % |
| | | $V_O = 4\text{ V}_{pp}$, $R_L = 2\text{ k}\Omega$, $A_V = +1$, $f = 10\text{ kHz}$ | | 0.01 | | |

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9. Guaranteed by design and/or characterization.

NCS2003/A, NCV2003, NCS20032, NCV20032, NCS20034, NCV20034

ELECTRICAL CHARACTERISTICS: $V_S = +5.0\text{ V}$

At $T_A = +25^\circ\text{C}$, $R_L = 10\text{ k}\Omega$ connected to midsupply, $V_{CM} = V_{OUT} = \text{midsupply}$, unless otherwise noted. **Boldface** limits apply over the specified temperature range. Guaranteed by design and/or characterization.

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit | | |
|------------------------------|----------|----------------------|--------------------|-----------|-----|------------|-------------|---------------|
| POWER SUPPLY | | | | | | | | |
| Power Supply Rejection Ratio | PSRR | NCx2003, A | | 72 | 80 | | dB | |
| | | | | 65 | | | | |
| | | NCx20032, NCx20034 | | 80 | 100 | | | |
| Quiescent Current | I_{DD} | No load, per channel | NCx2003, A | | | 300 | 660 | μA |
| | | | | | | | 1000 | |
| | | | NCx20032, NCx20034 | | | 325 | 450 | |
| | | | | | | 675 | | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

9. Guaranteed by design and/or characterization.

TYPICAL CHARACTERISTICS

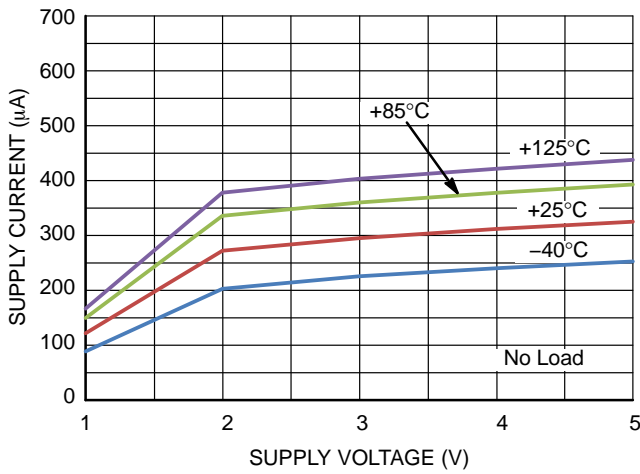


Figure 2. Quiescent Supply Current vs. Supply Voltage

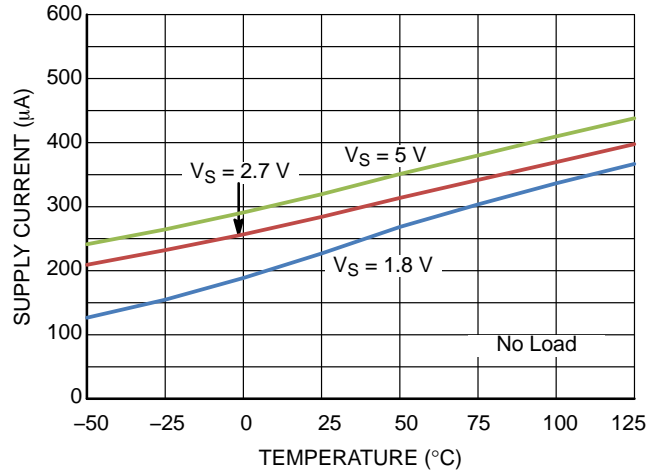


Figure 3. Quiescent Supply Current vs. Temperature

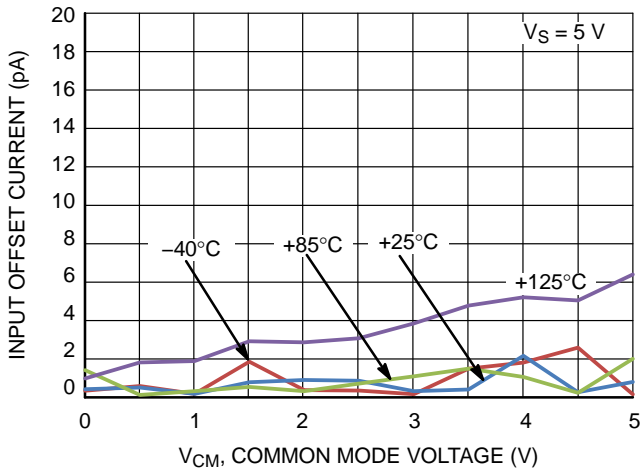


Figure 4. Input Offset Current vs. V_{CM}

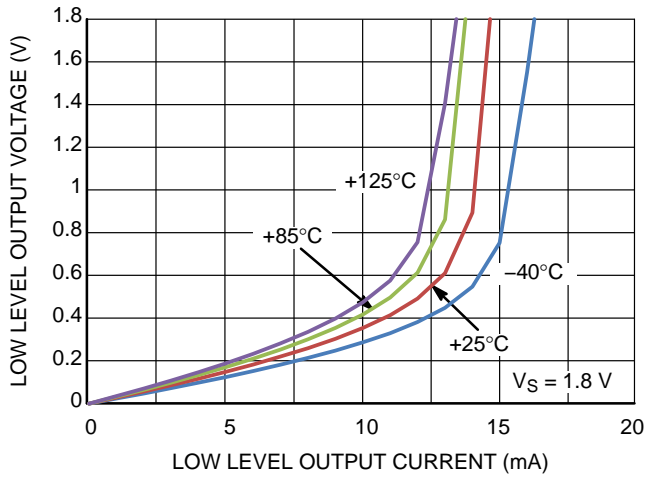


Figure 5. Low Level Output Voltage vs. Output Current @ $V_S = 1.8 V$

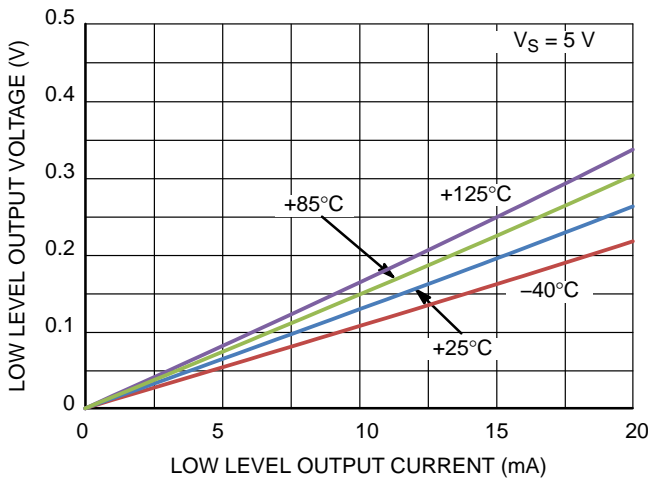


Figure 6. Low Level Output Voltage vs. Output Current @ $V_S = 5 V$

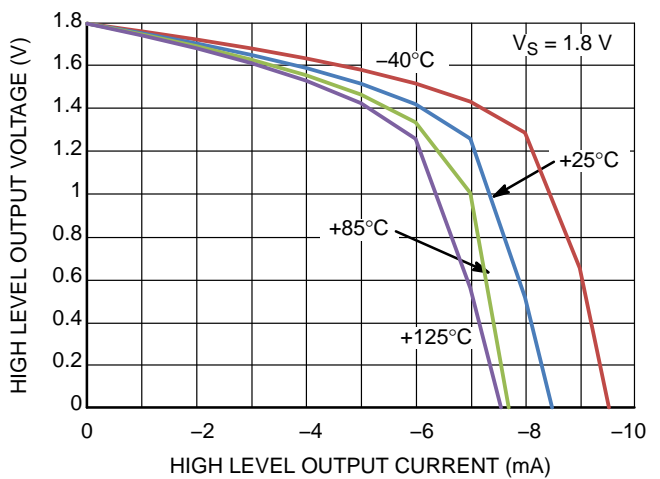


Figure 7. High Level Output Voltage vs. Output Current @ $V_S = 1.8 V$

TYPICAL CHARACTERISTICS

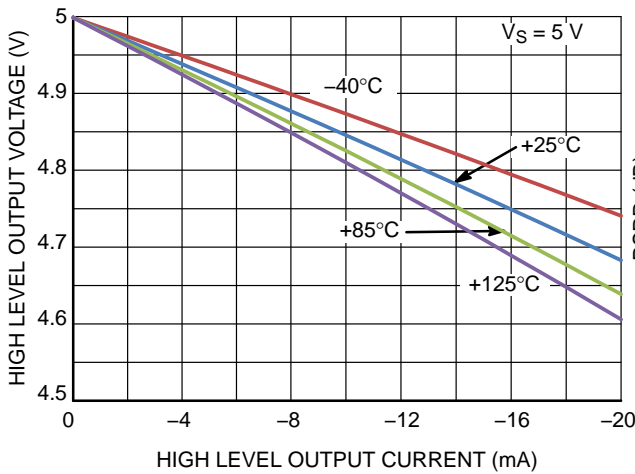


Figure 8. High Level Output Voltage vs. Output Current @ $V_S = 5\text{ V}$

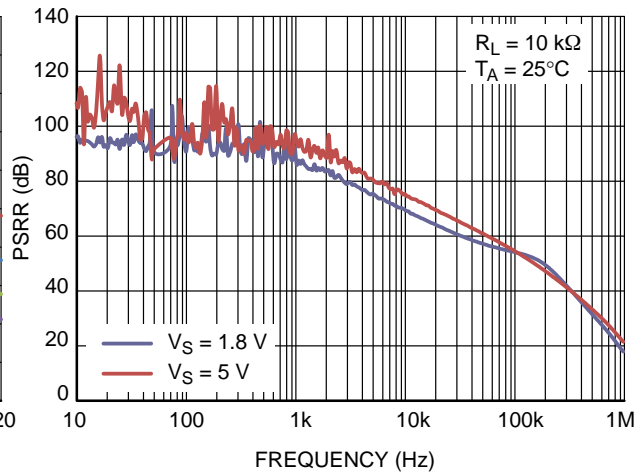


Figure 9. PSRR vs. Frequency

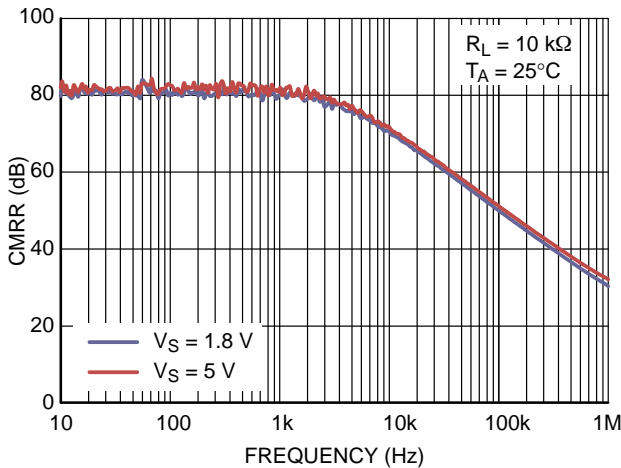


Figure 10. CMRR vs. Frequency

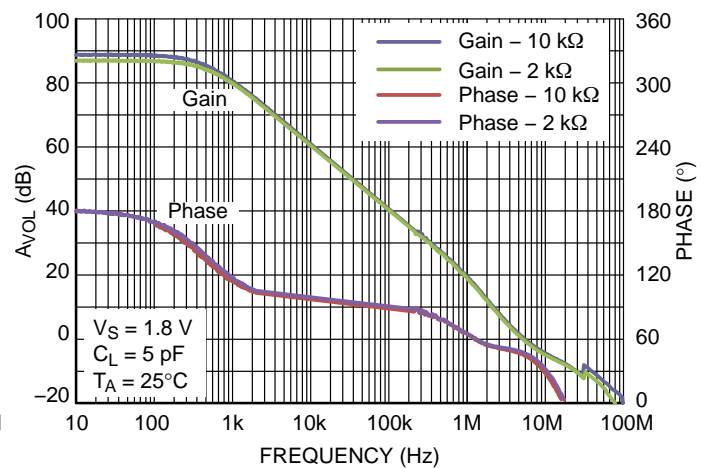


Figure 11. Open Loop Gain and Phase vs. Frequency @ $V_S = 1.8\text{ V}$

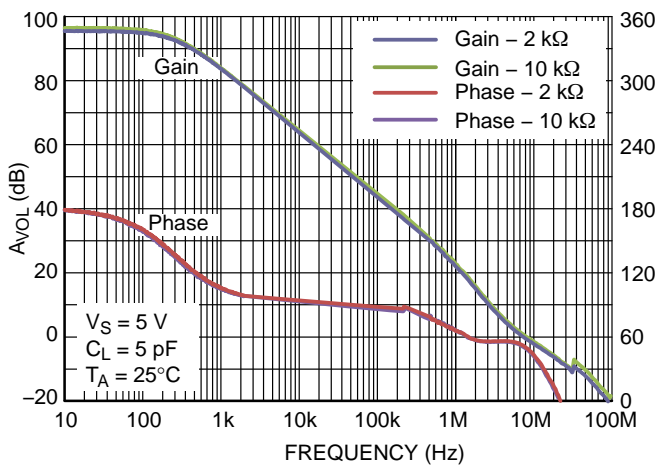


Figure 12. Open Loop Gain and Phase vs. Frequency @ $V_S = 5\text{ V}$

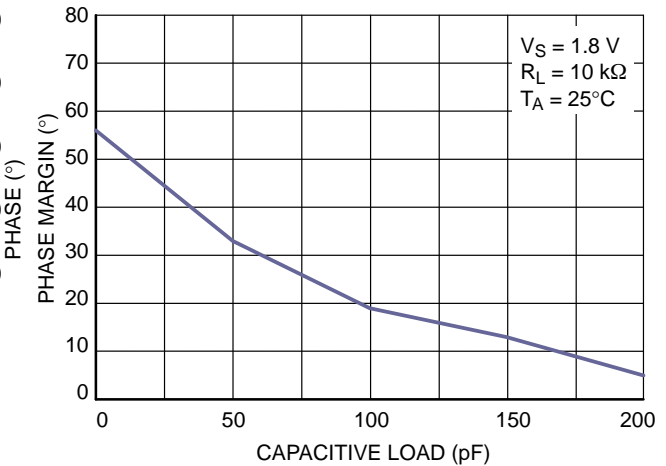


Figure 13. Phase Margin vs. Capacitive Load

TYPICAL CHARACTERISTICS

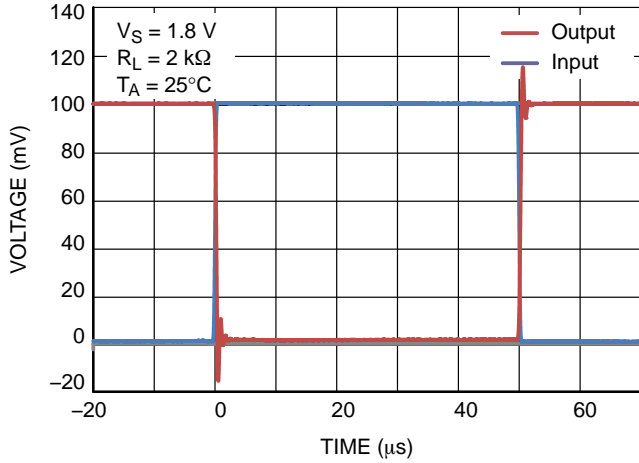


Figure 14. Inverting Small Signal Transient Response

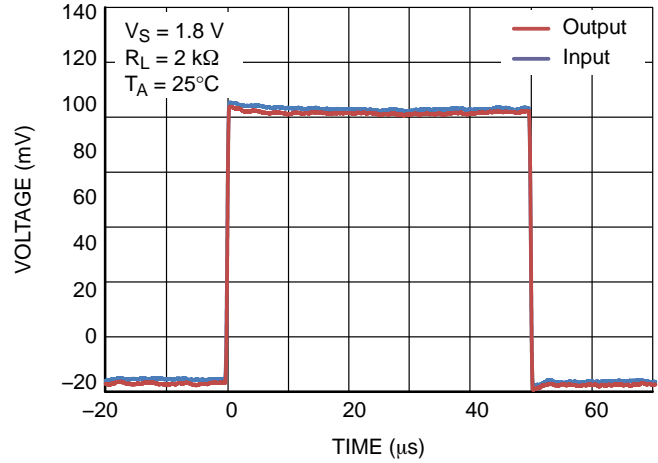


Figure 15. Non-Inverting Small Signal Transient Response

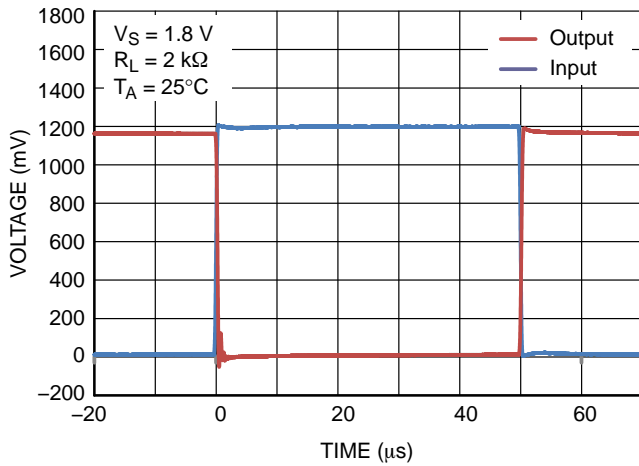


Figure 16. Inverting Large Signal Transient Response

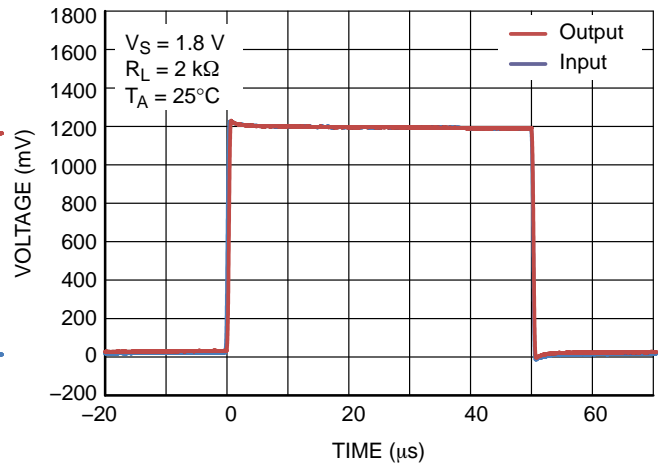


Figure 17. Non-Inverting Large Signal Transient Response

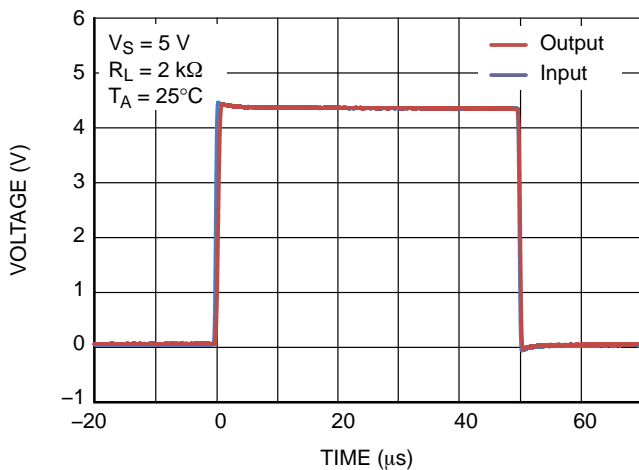


Figure 18. Non-Inverting Large Signal Transient Response

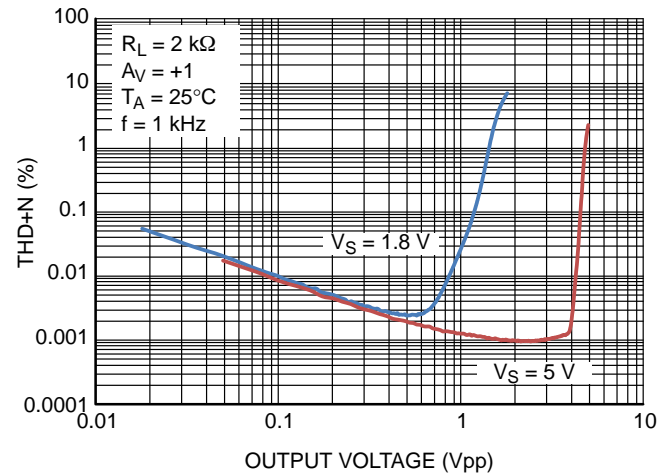


Figure 19. THD+N vs. Output Voltage

TYPICAL CHARACTERISTICS

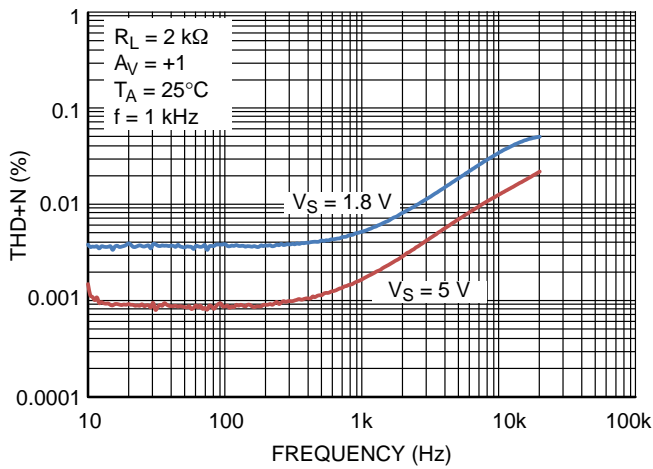


Figure 20. THD+N vs. Frequency

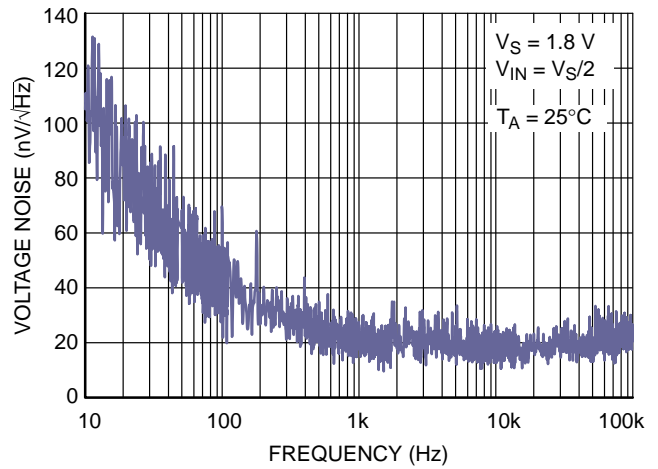


Figure 21. Input Voltage Noise vs. Frequency

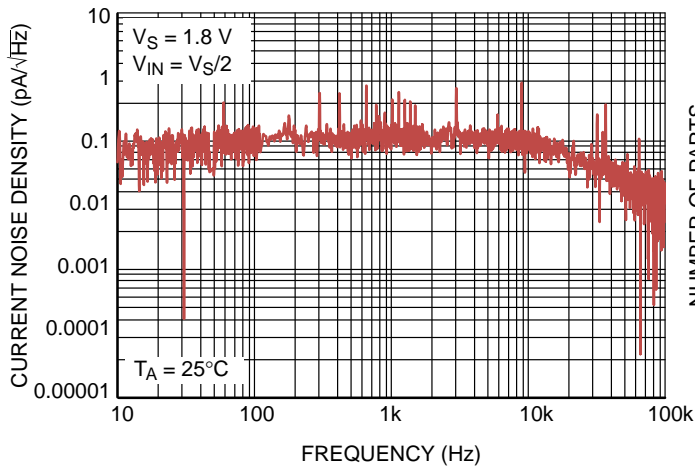


Figure 22. Noise Density vs. Frequency

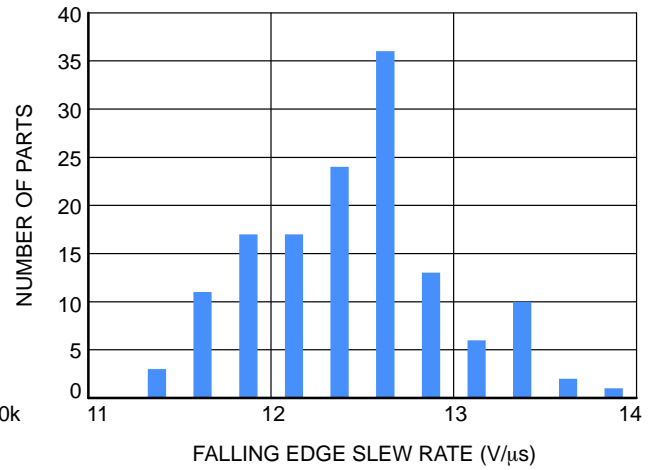


Figure 23. Falling Edge Slew Rate @ Vs = 5 V

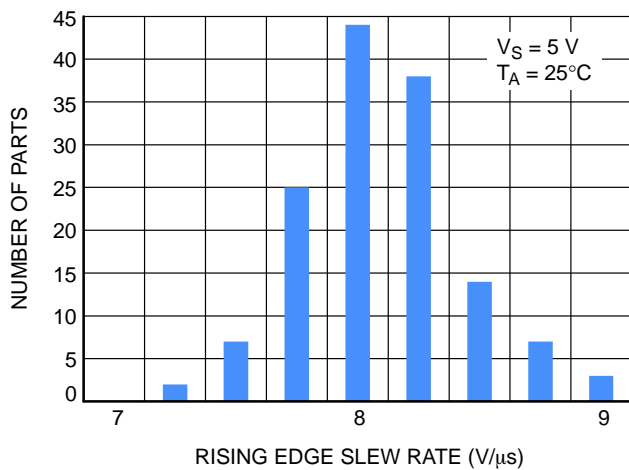


Figure 24. Rising Edge Slew Rate @ Vs = 5 V

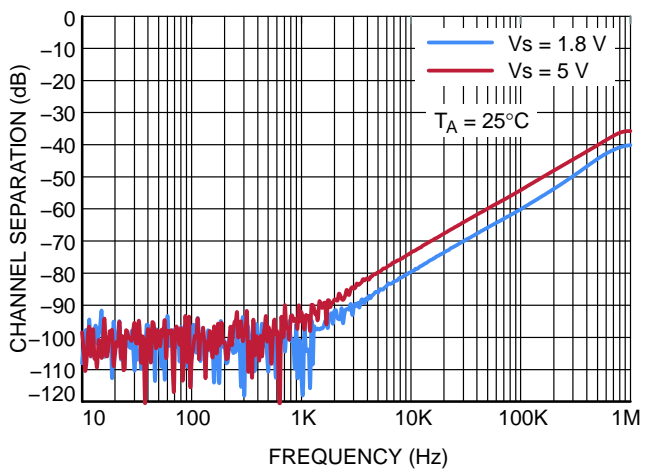
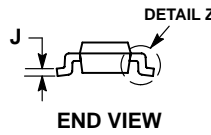
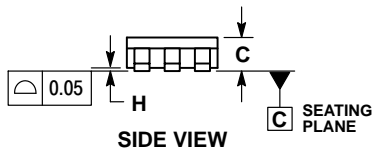
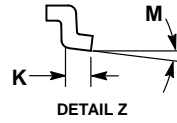
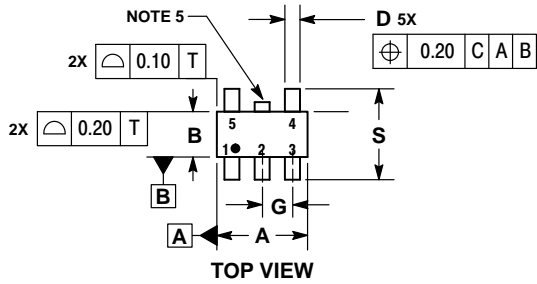


Figure 25. Channel Separation

PACKAGE DIMENSIONS

TSOP-5
CASE 483-02
ISSUE K

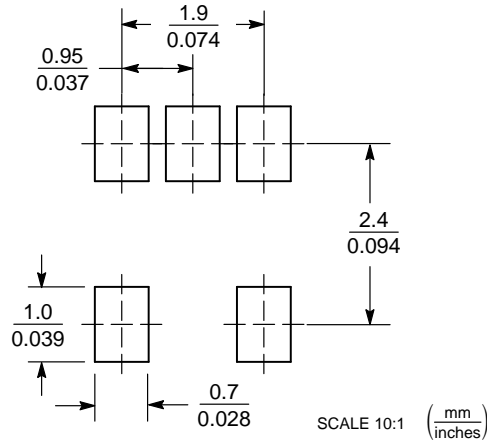


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A.
5. OPTIONAL CONSTRUCTION: AN ADDITIONAL TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 3.00 BSC | |
| B | 1.50 BSC | |
| C | 0.90 | 1.10 |
| D | 0.25 | 0.50 |
| G | 0.95 BSC | |
| H | 0.01 | 0.10 |
| J | 0.10 | 0.26 |
| K | 0.20 | 0.60 |
| M | 0° 10° | |
| S | 2.50 | 3.00 |

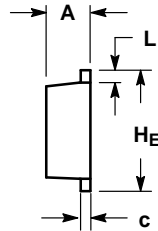
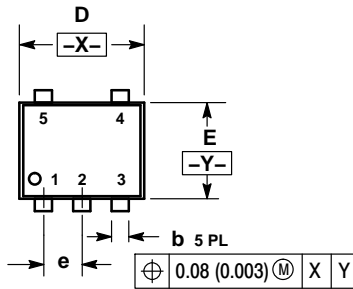
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-553, 5 LEAD
CASE 463B
ISSUE C

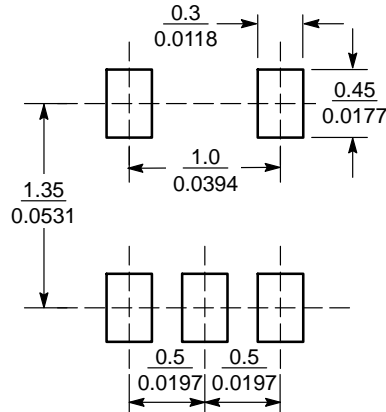


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.50 | 0.55 | 0.60 | 0.020 | 0.022 | 0.024 |
| b | 0.17 | 0.22 | 0.27 | 0.007 | 0.009 | 0.011 |
| c | 0.08 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |
| E | 1.15 | 1.20 | 1.25 | 0.045 | 0.047 | 0.049 |
| e | 0.50 BSC | | | 0.020 BSC | | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| HE | 1.55 | 1.60 | 1.65 | 0.061 | 0.063 | 0.065 |

RECOMMENDED
SOLDERING FOOTPRINT*

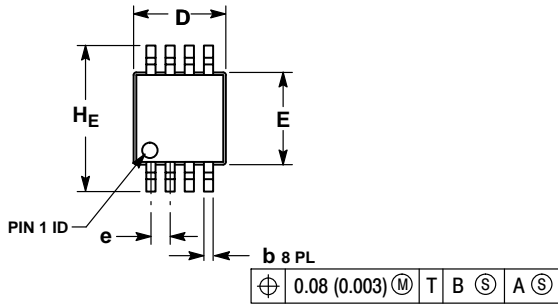


SCALE 20:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

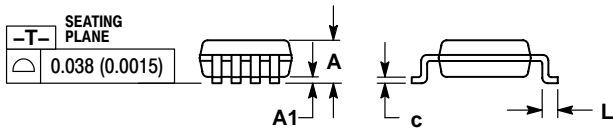
Micro8™
CASE 846A-02
ISSUE J



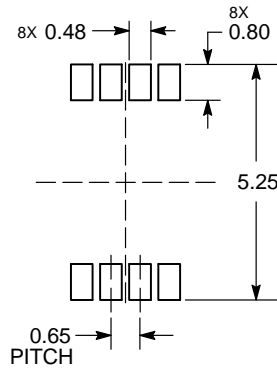
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|-----------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | — | — | 1.10 | — | — | 0.043 |
| A1 | 0.05 | 0.08 | 0.15 | 0.002 | 0.003 | 0.006 |
| b | 0.25 | 0.33 | 0.40 | 0.010 | 0.013 | 0.016 |
| c | 0.13 | 0.18 | 0.23 | 0.005 | 0.007 | 0.009 |
| D | 2.90 | 3.00 | 3.10 | 0.114 | 0.118 | 0.122 |
| E | 2.90 | 3.00 | 3.10 | 0.114 | 0.118 | 0.122 |
| e | 0.65 BSC | | | 0.026 BSC | | |
| L | 0.40 | 0.55 | 0.70 | 0.016 | 0.021 | 0.028 |
| HE | 4.75 | 4.90 | 5.05 | 0.187 | 0.193 | 0.199 |



RECOMMENDED
SOLDERING FOOTPRINT*

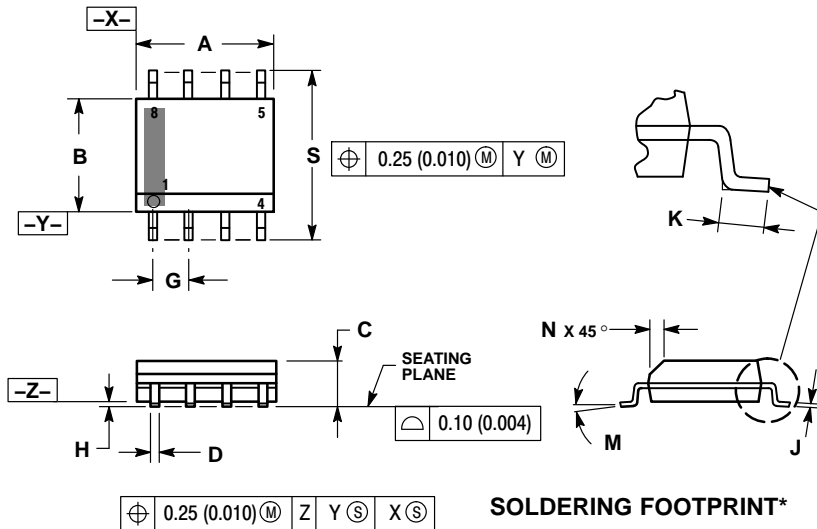


DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AK

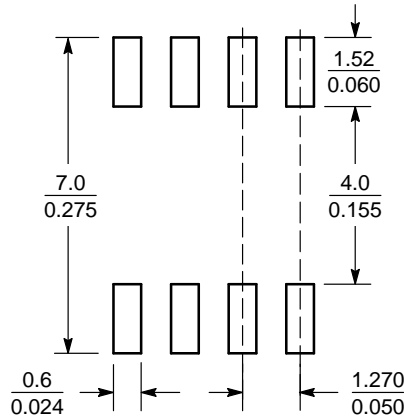


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC | | 0.050 BSC | |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0° - 8° | | 0° - 8° | |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

SOLDERING FOOTPRINT*

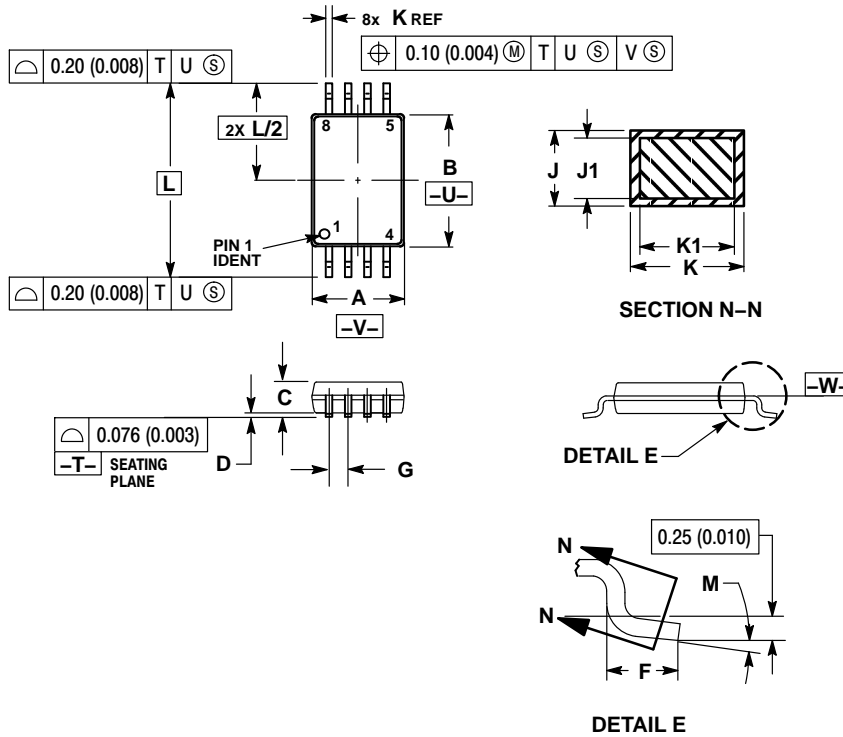


SCALE 6:1 ($\frac{\text{mm}}{\text{inches}}$)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8
CASE 948S
ISSUE C

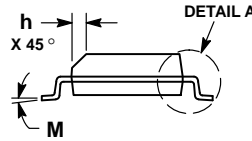
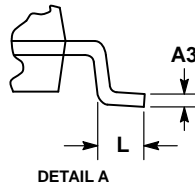
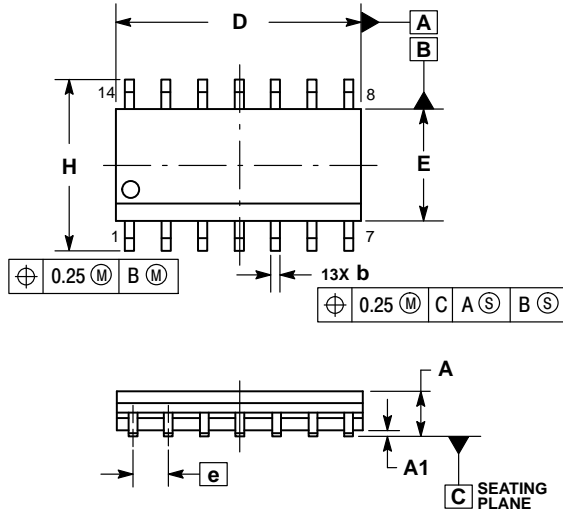


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 2.90 | 3.10 | 0.114 | 0.122 |
| B | 4.30 | 4.50 | 0.169 | 0.177 |
| C | --- | 1.10 | --- | 0.043 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.70 | 0.020 | 0.028 |
| G | 0.65 BSC | | 0.026 BSC | |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| M | 0° | 8° | 0° | 8° |

PACKAGE DIMENSIONS

SOIC-14 NB
CASE 751A-03
ISSUE K

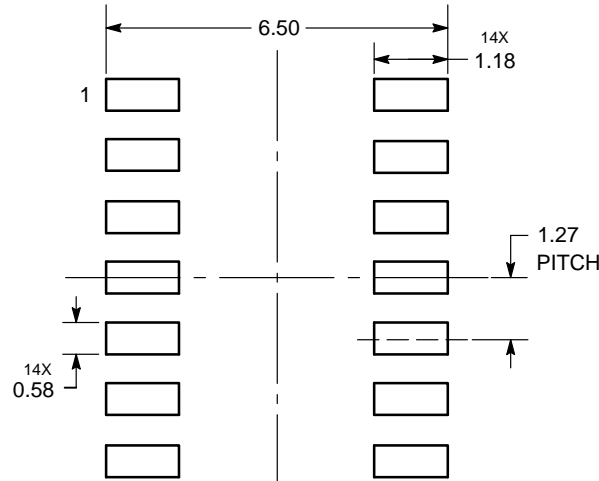


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| A3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| E | 3.80 | 4.00 | 0.150 | 0.157 |
| e | 1.27 BSC | | 0.050 BSC | |
| H | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| M | 0° | 7° | 0° | 7° |

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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